

# LS 4000 – Coater and Developer Systems



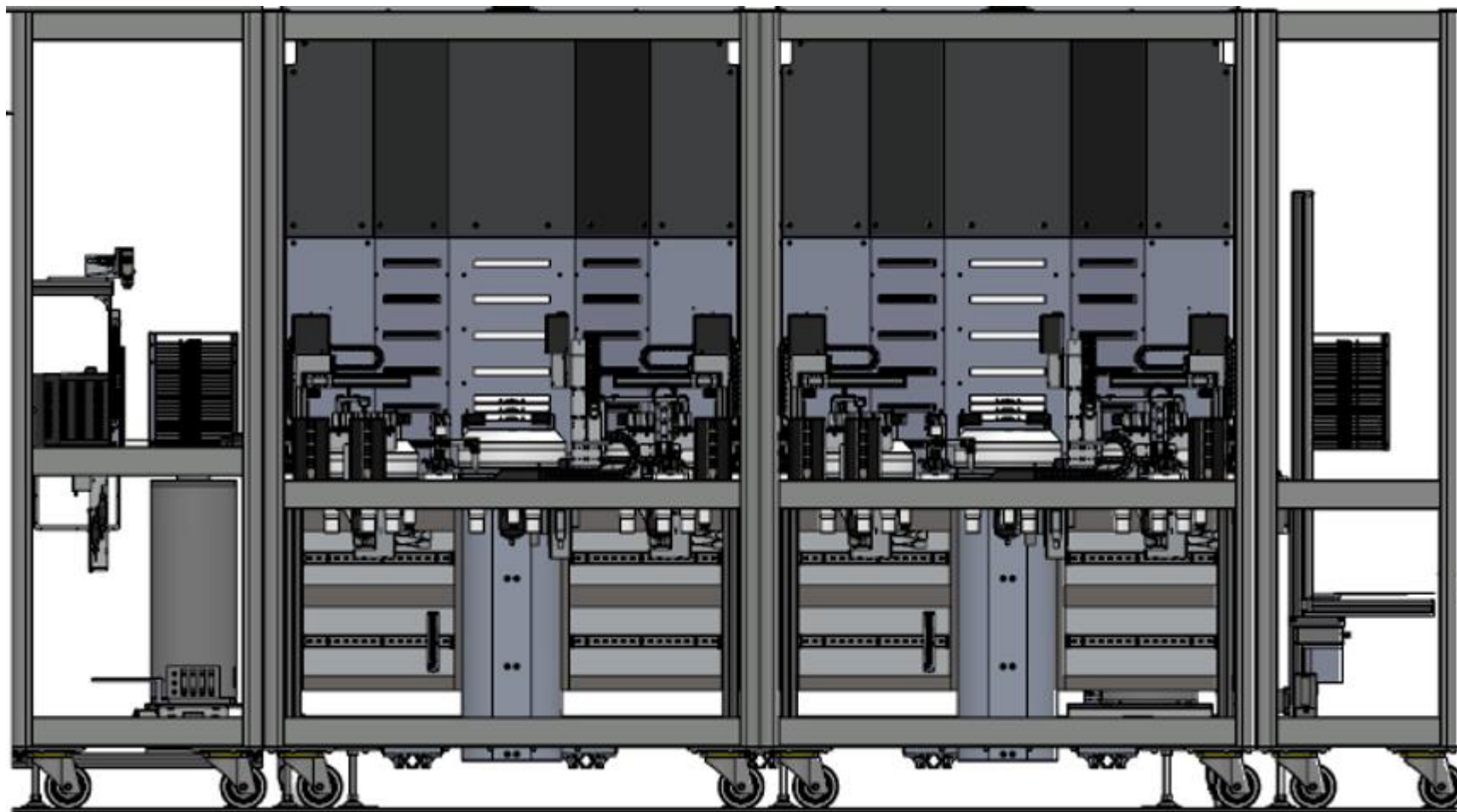
## Modular, flexible, expandable – Coater-Developer-Cluster System

LS 4000 coater - and developer system for wafer sizes up to 200mm with stepper interface offers maximum throughput for high volume production in combination with flexible system configuration for various process applications.

### System Features

- Flexible tool configuration with up to 12 processing modules and 4 I/O stations
- Wafer sizes up to 200mm diameter
- Available as cluster with stepper interface
- Up to 4 SMIF load ports for 200mm Wafer
- High throughput
- User friendly software allows upgrade of process modules and system components
- SECS/GEM interface
- Customer specific solutions

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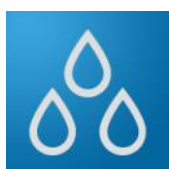
## Handling System

- 3-axis pick & place robots
- Contactless wafer centering "on-the-fly"
- OCR, bar and matrix code support
- Edge gripping of wafers available
- Intelligent cassette slot scanning detects carrier type, wafer size and double or cross loaded slots
- FOUP load ports can be integrated



## Coater Module

- Optimized bowl design with symmetric exhaust for optimal process results
- Programmable edge bead removal, wafer backside and bowl rinse
- Dispense system for up to 5 different media per bowl with automatic nozzle change
- Temperature controlled dispense lines
- Range of resist pumps to choose from:
  - » Customer-specific dispense system
  - » Trap tank dispense system
  - » Servo motor driven pump
  - » Syringe



## Developer Module

- Proven process bowl design with symmetric exhaust
- Dispense system for up to 3 different developer media per bowl
- Various developer media can be applied by:
  - » Puddle nozzle
  - » Fan spray nozzle
  - » Binary spray nozzle
- Programmable top-, backside & bowl rinse



## Hot- and Coolplate Module

- Up to 6 hot- or coolplates per module
- Standard hotplate (60°C - 200°C)
- High-temperature hotplate (60°C - 450°C)
- Hotplate with heated cover
- HMDS primer hotplate (60°C - 200°C)
- Coolplates (15°C - 45°C), with either water or Peltier cooling
- Distance control via
  - » Programmable proximity
  - » Fixed proximity

LithExx-Systems GmbH

Dellach 207  
A-9772 Dellach im Drautal  
Austria

Phone: +43 4242 30848  
Fax: +43 4242 30848-10

office@lithexx-systems.com  
www.lithexx-systems.com